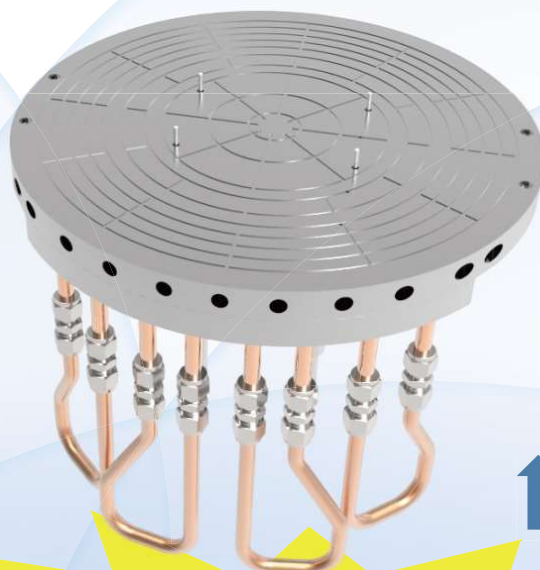


Wafer Rapid Heating/Cooling Module

晶圓快速加熱/水冷盤座

Heating/Cooling
stage



Control box

Rapid heating $>2\text{ }^{\circ}\text{C}/\text{sec}$
Rapid cooling $>3\text{ }^{\circ}\text{C}/\text{sec}$
High throughput

FEATURES :

1. Stage design with integrated heating / cooling
升溫/水冷的一體式設計
2. Withstand thermal shock deformation design
可承受熱衝擊變形設計
3. Wafer vacuum adsorption design
晶圓真空吸附設計
4. High-precision surface processing
高精度表面加工
5. The control box can be matched with the customer's main system
控制箱可與客戶主系統配套



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APPLICATIONS :

1. Wafer rapid heating / cooling module , improve throughput

晶圓快速加熱/水冷盤座 , 提高產速

2. Thin product application for other industries (glass)

其他產業的薄型件產品應用 (如玻璃)



Actual application photo

SPECIFICATION:

ITEM	SPECIFICATION
Wafer size	6 / 8 / 12 inch
Mouldle size	Max Φ 320mm
Stage thickness	20mm
Power supply	AC 220V 50/ 60 Hz 1 Φ
Temp. setting range	50-250 $^{\circ}$ C
Temp. rise rate	\geq 2 $^{\circ}$ C
Temp. cooling rate	\geq 3 $^{\circ}$ C